

[会告]

第6回アジア溶射会議 ATSC2014 開催について

アジア各国の溶射関係者が一堂に集い、最新の溶射技術の成果を発表するアジア溶射会議 (ATSC)。一昨年 11 月にわが国つくば市にて ATSC2012 が開催されたことは会員各位様の記憶にもまだ新しいのではないのでしょうか。

来年 2014 年には初めてインド、ハイデラバード市にて開催されることとなりました。この機会にぜひ第6回アジア溶射会議 ATSC2014 に参加して、アジアの溶射の潮流を感じ取ってください。

開催の詳細は開催者からの講演募集案内 (First Call for Paper) をご覧ください。開催内容の概要は以下の通りです。

1. 会議名：第6回アジア溶射会議 6th Asian Thermal Spray Conference
2. 開催日時： 2014年11月24日～26日
3. 開催場所： ハイデラバード市 インド
4. 主催者： International Advanced Research Centre for Powder Metallurgy and New Materials (ARCI)
5. 講演申込み期日
アブストラクト投稿締切 2014年5月1日
予稿原稿締め切り 2014年9月15日
講演大会 2014年11月24-26日
6. 費用
外国からの個人参加者 300US\$
外国からの学生参加者 200US\$



6th Asian Thermal Spray Conference

24th-26th November 2014
Hyderabad, India



Organized by

**International Advanced Research Centre
for Powder Metallurgy and New Materials (ARCI)
Hyderabad, India**

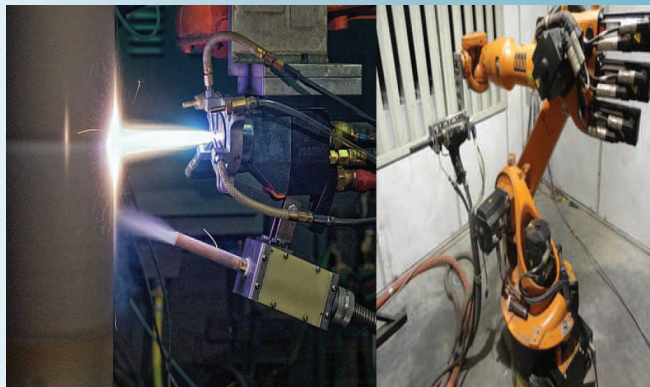
In association with

Asian Thermal Spray Society



About ATSC

The Asian Thermal Spray Conference (ATSC), following concerted efforts by all segments of the thermal spray community in the member countries, has emerged as a flagship event in the Asia-Pacific region. The major objective of the event is to provide an attractive forum for all stakeholders (researchers from industry, R&D institutions and academia; practitioners from thermal spray service providers; equipment and feedstock manufacturers as well as OEMs and users) from across the region to interact in order to foster a fruitful interaction during and after the conference.



The event is also expected to provide an ideal platform for young researchers and engineers to familiarize themselves with recent advances in this rapidly evolving, yet industrially well-entrenched technology as well as for various companies to exhibit relevant products to a dedicated audience. The past editions of the event organized in Japan, Korea, Singapore and China were extremely successful in realizing the above objectives. The 6th edition of ATSC will be held in India for the first time in the city of Hyderabad from 24-26th of November 2014.

Call for Papers

The Technical Program at the 6th ATSC will address diverse aspects related to thermal spray science and technology, ranging from fundamental research to industrial applications. Prospective authors are invited to submit abstracts of papers dealing with, but not restricted to, any of the several themes listed below:

- Cold Spray/Kinetic Spray
- Solution and Suspension based Spray Processes
- Advances in Thermal Spray Processes
- Hybrid Spray Processes
- Thermal Barrier Coatings
- Repair & Refurbishment
- Wear & Corrosion Protection
- Novel Functional Applications
- Modeling & Simulation
- Process Control & Diagnostics
- Processing-Structure-Property correlations
- Advanced Characterization of Coatings
- Mechanical Properties of Coatings
- Environmental/Occupational Safety
- Advanced Material Systems

An abstract of approximately 500 words, in English, together with full contact details, should reach the Conference Secretariat no later than **1st May 2014**. Abstracts received shall be considered for both Oral and Poster Presentation. Those authors specifically preferring poster presentations should indicate so. Short manuscripts of all accepted papers to be presented at ATSC 2014, orally or in poster form, will be included in proceedings to be published in a book form. In order to ensure that the publication exercise is accomplished on schedule to make the proceedings available to the participants during ATSC 2014, complete manuscripts (prepared according to guidelines to be issued subsequently) will be due by 15th September 2014. Efforts are also being made to have selected papers appear as part of a special issue of Journal of Thermal Spray Technology dedicated to ATSC 2014.

Confirmed Speakers

Even before the circulation of the first call for papers, the conference has enthused considerable all round interest with leading experts in the field consenting to deliver Plenary/Invited lectures. Some of the confirmed speakers are listed below:

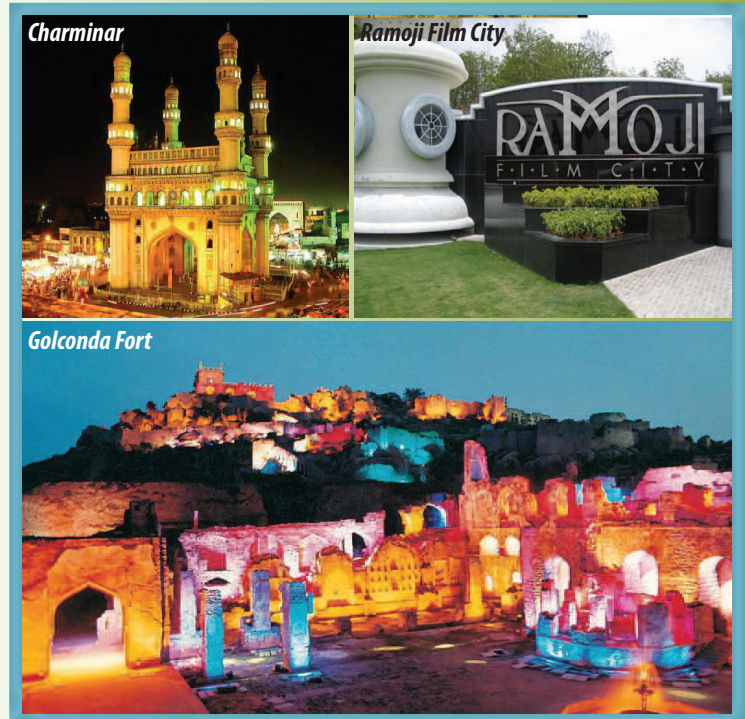
- Chang Jiu Li, Xi'an Jiaotong University, China
- Changhee Lee, Hanyang University, Korea
- Christian Moreau, Concordia University, Canada
- Christopher Berndt, Swinburne Uni. of Technology, Australia
- William Clyne, Cambridge University, UK
- KA Khor, NTU, Singapore
- Seiji Kuroda, NIMS, Japan
- Sanjay Sampath, Stony Brook University, USA
- Richard Schmid, Sulzer Metco, Switzerland
- G Sundararajan, ARCI, India
- Armelle Vardelle, University of Limoges, France
- Arvind Agarwal, Florida International University, USA
- Jun Akedo, Advanced Indl. Science & Technology, Japan
- M Fukumoto, Toyohashi University, Japan
- J Karthikeyan, ASB Ind., USA
- K Ogawa, Tohoku University, Japan

Venue

ATSC 2014 will be organized in the South Indian city of Hyderabad. Besides having an international airport of its own with direct flights from many overseas destinations, Hyderabad is also well-connected with all other Indian cities. One of the oldest cities in India with a great and unbroken history, Hyderabad is a bustling 400 year old metropolis with an urban population of well over 4 million. The city is cosmopolitan, and is richly endowed with a variety of cultures. The city presents an attractive amalgam of old world charm together with the ebullience of growth and enterprise. Widely accepted as the "research capital of India" and already a prominent IT hub, Hyderabad is a place where modern sophistication blends majestically with rich tradition handed down the ages from a glorious history. Reliving the past is a rejuvenating experience in this city where old monuments and mausoleums attract the tourists. Opportunities for shopping abound in this "pearl city" and the famous Hyderabadi cuisine is also certain to tickle any visitor's palate. Hyderabad is at an altitude of 536 meters above sea level with pleasant temperatures ranging between 15-30 degrees Celsius expected during the Conference.

Exhibition

An exhibition will be held in parallel with the conference, offering a great opportunity for companies to exhibit their products/equipment or advertise their capabilities to a wide cross-section of the surface treatment community. The market potential in India for surface engineering related products and services is enormous and ATSC 2014 is a unique event that will bring exhibitors face to face with prospective customers from academic institutes, research organizations and industry. Attractive sponsorship opportunities are also available. Further details can be obtained from the Conference Secretariat.



Important Dates

Submission of Abstract	1 st May 2014
Submission of Short Manuscript for Proceedings	15 th September 2014
Conference	24-26 th November 2014

First Announcement & Call for Papers

Registration Charges

Category	Foreign Participant	Indian Participant
Oral presentation/ Poster Presentation/ Participation	300 US\$	8000 INR
Student	200 US\$	4000 INR

The above indicated registration fee for Indian participants reflects the subsidy made possible by funds expected from by Government sponsoring agencies. The registration fee entitles (a) entry to all technical sessions (b) refreshments & lunches on all conference days and (c) conference kit. Accommodation is not included. An Early Registration Discount of 10% will be applicable to all participants who register before June 1, 2014.

Contact Details

Convenor

Dr Shrikant V Joshi,
 Additional Director, ARCI

Co-Convenor

Shri D Srinivasa Rao,
 Team Leader, Centre for Engineered Coatings, ARCI

6th Asian Thermal Spray Conference

International Advanced Research Centre for Powder Metallurgy & New Materials (ARCI)

Balapur Post, Hyderabad - 500 005, INDIA

Phone: 0091-40-24441077, 24452374, 24452470; Fax: 0091-40-24443168

Email: atsc2014@arci.res.in

